#### **ABSOLUTE MAXIMUM RATINGS**

IN, SHDN, RCS, FAULT, OUT to GND	0.3V to +6V
PGND to GND	
CXN to GND	0.3V to (V <sub>IN</sub> + 0.3V)
CXP to GND	0.3V to (V <sub>CEXT</sub> + 0.3V)
CEXT to GND	0.3V to (V <sub>CEXT</sub> + 0.3V)
Short-Circuit Duration to GND	Indefinite

Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )

10-Pin μMAX	
Operating Temperature Range	
Junction Temperature	+150°C
Storage Temperature Range	
Lead Temperature (soldering, 10s)	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{IN} = \overline{SHDN} = 3V, C_{IN} = 4.7\mu$ F,  $C_X = 0.68\mu$ F,  $C_{EXT} = 6.8\mu$ F,  $C_{OUT} = 4.7\mu$ F,  $R_{CS} = 0.4\Omega$ ,  $T_A = 0^{\circ}$ C to +70°C, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}$ C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS		
Input Voltage Range	Maria	$I_{OUT} = 125 \text{mA}, 4.75 \text{V} \le \text{V}_{OUT} \le 5.25 \text{V}$		$I_{OUT} = 125 \text{mA}, 4.75 \text{V} \le \text{V}_{OUT} \le 5.25 \text{V}$ 2.	2.95		4.25	v
(Note 1)	VIN	I <sub>OUT</sub> = 70mA	2.95		5.50	V		
Input Undervoltage Lockout Threshold		Rising edge	2.0	2.35	2.6	V		
Input Undervoltage Lockout Hysteresis		Falling edge		100		mV		
Output Voltage	Vour	$0 \le I_{OUT} < 30$ mA, 2.95V < $V_{IN} < 5.5$ V	4.75	5.0	5.30	V		
(Note 2)	Vout	$0\text{mA} \le I_{OUT} \le 125\text{mA}, 2.95\text{V} \le \text{V}_{IN} \le 4.25\text{V}$	4.75	5.0	5.25	25 V		
Output Voltage Ripple	V <sub>RIP</sub>	$0mA \le I_{OUT} \le 125mA$		100		mV		
V <sub>OUT</sub> Fault Threshold	V <sub>TH</sub>	$V_{OUT} = 5V$ (nominal), no load	82.5		92.5	%Vout		
Maximum Output Current	IOUT	$V_{OUT} = 5V \pm 4\%$	100	140		mA		
	IQ	$I_{OUT} = 0, V_{IN} = 4.25V$		0.6				
No-Load Input Current		$I_{OUT} = 0, V_{IN} = 3.3V$		1	6	mA		
SHDN Logic High	VINH, SHDN		2.4			V		
SHDN Logic Low	VINL, SHDN				0.4	V		
Shutdown Supply Current	IQ <del>SHDN</del>	SHDN = low		0.1	10	μA		
Current-Sense Trip Level	VCS	V <sub>CS</sub> = I <sub>OUT</sub> x R <sub>CS</sub> (Note 3)	55	60	73	mV		
FAULT Leakage Current		$V_{FAULT} = 5V, OUT$ in regulation			1	μA		
FAULT Logic Low		IOUT > ILIMIT, OR VOUT < VTH, IFAULT = 1mA			0.4	V		
FAULT Assertion Delay		Iout > Ilimit		2		ms		
(Note 4)	tfD	V <sub>OUT</sub> < V <sub>TH</sub>		30		μs		
FAULT Deassertion Delay (Note 5)	tfdd	$I_{OUT} < I_{LIMIT}$ and $V_{OUT} > 4.5V$		16		ms		
Switching Frequency			0.5	1	1.5	MHz		
Startup Time	<b>t</b> START	$V_{OUT}$ > $V_{TH},$ $R_{LOAD}$ = 46 $\Omega,$ from rising edge of $\overline{SHDN}$		200		μs		

**MAX5008** 

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN} = \overline{SHDN} = 3V, C_{IN} = 4.7\mu F, C_X = 0.68\mu F, C_{EXT} = 6.8\mu F, C_{OUT} = 4.7\mu F, R_{CS} = 0.4\Omega, T_A = 0^{\circ}C$  to +70°C, unless otherwise noted. Typical values are at T<sub>A</sub> = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
Thermal Shutdown Junction Temperature				150		°C
Thermal Shutdown Hysteresis				30		°C

Note 1: When the input exceeds 4.25V, the power dissipation on the chip exceeds the maximum rating if the output current is 125mA.

Note 2: The MIN/MAX limits are 100% production tested at +25°C and +70°C, and guaranteed by design at 0°C.

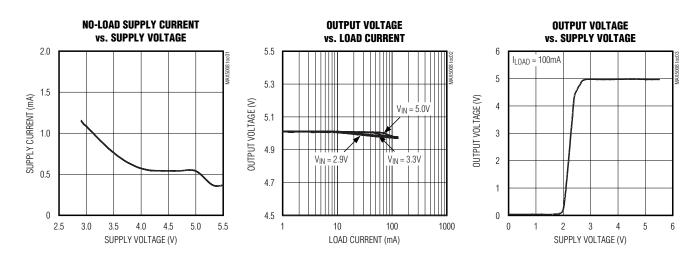
Note 3:  $I_{OUT}$  is output current flowing from  $C_{EXT}$ .

Note 4: The delay from the fault event to the assertion of FAULT. Fault delays are specified with either a current fault or a voltage fault, but not both simultaneously.

Note 5: The delay from the removal of the fault event to the deassertion of FAULT.

### **Typical Operating Characteristics**

 $(V_{IN} = 3V, C_{IN} = 4.7\mu\text{F}, C_X = 0.47\mu\text{F}, C_{OUT} = 4.7\mu\text{F}, C_{EXT} = 4.7\mu\text{F}, R_{CS} = 0.4\Omega, T_A = +25^{\circ}\text{C}, \text{ unless otherwise noted.})$ 



#### **Typical Operating Characteristics (continued)**

 $(V_{IN} = 3V, C_{IN} = 4.7\mu F, C_X = 0.47\mu F, C_{OUT} = 4.7\mu F, C_{EXT} = 4.7\mu F, R_{CS} = 0.4\Omega, T_A = +25^{\circ}C, unless otherwise noted.)$ 

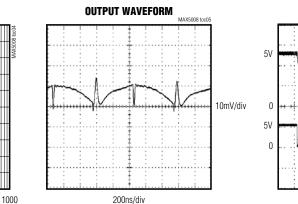
EFFICIENCY vs. LOAD CURRENT V<sub>IN</sub> = 2.95V

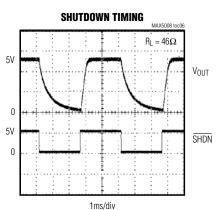
10

LOAD CURRENT (mA)

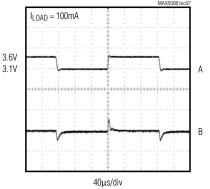
3.3V

100



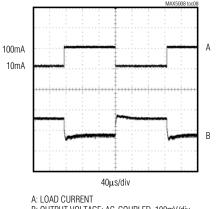


LINE-TRANSIENT RESPONSE



A: INPUT VOLTAGE: 500mV/div B: OUTPUT VOLTAGE: AC-COUPLED, 100mV/div

LOAD-TRANSIENT RESPONSE



B: OUTPUT VOLTAGE: AC-COUPLED, 100mV/div

100

90

80

70

50 40

30

20 10 0

1

EFFICIENCY (%) 60

## \_Pin Description

PIN	NAME	FUNCTION			
1	RCS	External Current-Sense Resistor. Connect a resistor from RCS to OUT to set the overcurrent threshold. $I_{LIMIT}$ = 60mV / $R_{CS}.$			
2	OUT	Fixed 5V Output. Bypass OUT to GND with a 4.7µF capacitor.			
3	FAULT	Output Fault Indicator. $\overline{FAULT}$ is asserted when either I <sub>OUT</sub> > I <sub>LIMIT</sub> or V <sub>OUT</sub> < V <sub>TH</sub> . $\overline{FAULT}$ is an open-drain output that is high during normal operation or during shutdown.			
4	GND	Ground Pin. Connect GND to PGND.			
5	SHDN	$\overline{N}$ Shutdown Input. When $\overline{SHDN}$ = low, the device turns off. Drive $\overline{SHDN}$ high or connect to IN for normal operation.			
6	PGND	Power Ground Pin. Connect PGND to GND.			
7	CXN	Negative Terminal of the Charge-Pump Capacitor. Connect a 0.68µF capacitor from CXN to CXP.			
8	IN	Input Supply, 2.95V to 5.5V. Bypass IN to GND with a 4.7µF ceramic capacitor.			
9	CXP	Positive Terminal of the Charge-Pump Capacitor. Connect a 0.68µF capacitor from CXP to CXN.			
10	CEXT	Charge-Pump Output. Bypass CEXT to PGND with a 6.8µF capacitor.			

### **Detailed Description**

The MAX5008 charge pump provides a regulated 5V output from a 2.95V to 5.5V input. The device delivers a maximum of 125mA load current. Designed specifically for compact applications, a complete regulator circuit requires a minimum number of external components.

#### **Adjustable Current Limit**

The MAX5008 has an adjustable overcurrent protection. An external current-sense resistor is connected from RCS to OUT to set the current limit. The current limit is defined by:

#### $I_{LIMIT} = V_{CS} / RCS$

where V\_CS is the current-sense trip level, typically 60mV. For example,  $I_{LIMIT}$  = 150mA when RCS =  $0.40\Omega.$ 

When the output current limit is exceeded, the output voltage falls and the device maintains the average output current at  $I_{\text{LIMIT}}$ . Upon removal of the overcurrent condition, the part resumes normal operation.

#### **FAULT** Indication

When  $I_{OUT} > I_{LIMIT}$  or  $V_{OUT} < V_{TH}$ , FAULT asserts. FAULT is an open-drain output that needs to be connected through a  $100k\Omega$  (typ) pullup resistor to a logic supply voltage.

#### **Thermal Shutdown**

The MAX5008 has internal thermal shutdown circuitry, which shuts down the device when the die temperature exceeds  $+150^{\circ}$ C. The thermal shutdown circuitry has  $30^{\circ}$ C hysteresis.

#### Shutdown Mode

Driving SHDN low places the device in shutdown mode, which disables the oscillator, the control logic, and the reference. The output goes into high-impedance state and drops to ground if loaded. Placing the device in shutdown mode reduces the supply current to less than 0.1µA. In normal operation, SHDN is driven high or connected to IN.

## **Applications Information**

#### **Capacitor Selection**

The MAX5008 requires four external capacitors. Their values depend on the required output current. Table 1 shows the capacitor values recommended for different load currents.

#### **Input Voltage Range**

The MAX5008 maintains a regulated 5V output with input voltages from 2.95V to 5.5V. If the input voltage exceeds 4.25V, limit the output current to 75mA or less. This keeps the MAX5008 within its maximum power dissipation limits.

#### Table 1. Recommended Capacitor Values

Ιουτ	C <sub>IN</sub> (μF)	Сχ (μF)	C <sub>EXT</sub> (µF)	Cout (μF)
50mA	3.3	0.33	3.3	3.3
125mA	4.7	0.68	6.8	4.7

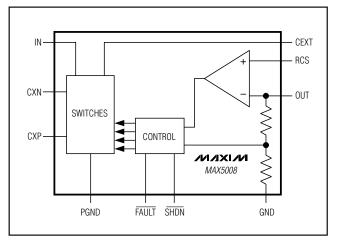
#### **Layout Considerations**

All capacitors should be located as close to the IC as practical. Connect GND and PGND through a short,

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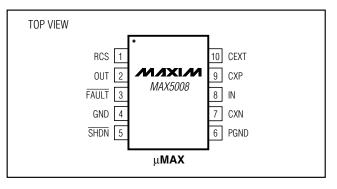
**MAX5008** 

### Functional Diagram



low-impedance trace, and connect the ground for  $C_{\rm IN},$   $C_{\rm EXT},$  and  $C_{\rm OUT}$  directly to PGND in a star configuration. Connect  $R_{CS}$  to  $C_{\rm EXT}$  through a short and low impedance trace.

## \_\_\_\_\_Pin Configuration

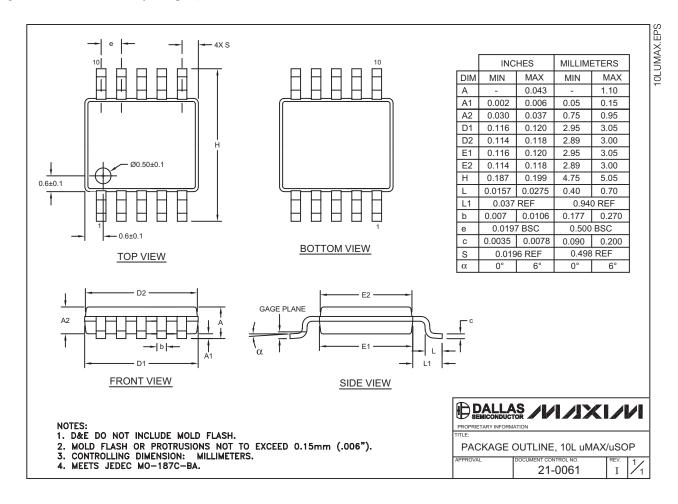


### Chip Information

TRANSISTOR COUNT: 2632 PROCESS: BICMOS

### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



### **Revision History**

Pages changed at Rev 1: 1, 2, 7

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**MAX5008** 

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